



EZBOND[®] SG 641

HEAT SINK COMPOUND

EZBOND[®] SG 641 heat sink compound is a grease like silicone material. The combination insures high thermal conductivity, low bleed and high-temperature stability

- Excellent heat conductivity
- Excellent adhesion
- It dose not affect on silicone rubber
- Low oil separations
- Meet with ROHS



RoHS Compliant

USES

EZBOND[®] SG 641 heat sink compound is applied to the base and mounting studs of transistors and diodes and silicon controlled devices. It is also an effective thermal coupler for any heat sink device where efficient cooling is required.

TYPICAL PROPERTIES

Appearance	White grease type
Work penetration(25°C)	240-320
Specific Gravity	2.3
Thermal Conductivity(W/mK)	1.0
Thermal Impedance (°C/W) @15 psi	0.35
Bleed (%) 200°C @24 hrs	0.01
Evaporation(wt%, 200X24hr)	< 0.3
Dielectric strength(V/mil) ASTM D149	220
Volume resistivity(Ω-cm) ASTM D257	3 ×10 ¹⁴

* These values are not intended for use in preparing specifications.

PACKAGING

1kg plastic can, 3kg plastic can, 15kg pail, 180kg steel drum